



Material Declaration Sheet

- Device : ASFC128G32T5-51BIN
 - Package : 11.5 x 13.0 153ball FBGA eMMC
 - Weight (mg) : 296.9504mg

Material	Component wt (mg)	Purpose	Substances	CAS No.	Weight (mg)	wt % of Total unit wt	Element wt (%)	PPM	
Printed Circuit Board	69.6772	Au	Au Plating	7440-57-5	0.1806	0.06%	0.20%	608	
			Ni	Ni Plating	7440-02-0	1.4043	0.47%	1.57%	4729
			Cu	Cu Plating	7440-50-8	60.2458	20.29%	67.18%	202882
		Core	Copper foil	7440-50-8	9.6540	3.25%	10.77%	32510	
			E-Glass Fabric	65997-17-3	9.6540	3.25%	10.77%	32510	
		Solder Mask	Poly(acrylic acid)	Trade Secret	3.4871	1.17%	3.89%	11743	
			Barium sulfate	7727-43-7	2.0954	0.71%	2.34%	7056	
			3-Methoxy-2-methylbutyl Acetate	102429-90-9	1.0238	0.34%	1.14%	3448	
			Dipropylene Glycol Monomethyl Ether	34590-94-8	0.8861	0.29%	0.97%	2917	
			Talc	14807-96-6	0.2128	0.07%	0.24%	717	
			Photopolymerization	Trade Secret	0.2128	0.07%	0.24%	717	
			Solvent naphtha	64742-94-5	0.2128	0.07%	0.24%	717	
			Auxiliaries	Trade Secret	0.2128	0.07%	0.24%	717	
			Silicon dioxide	Trade Secret	0.0412	0.01%	0.05%	139	
			Phthalocyanine blue	Trade Secret	0.0412	0.01%	0.05%	139	
			Organic pigment	Trade Secret	0.1324	0.04%	0.15%	446	
			Chip Capacitor	3.2000	Ceramic element	Barium oxide, obtained by calcining whiterite	1304-28-5	1.2780	0.43%
Titanium dioxide	13463-67-7	0.6390				0.22%	19.97%	2152	
Misc	-	0.2130				0.07%	6.66%	717	
Outer electrode	Copper	7440-50-8			0.3438	0.12%	10.74%	1158	
	diboron trioxide; boric oxide	1303-86-2			0.0076	0.00%	0.24%	26	
	Silicon dioxide	7631-86-9			0.0306	0.01%	0.96%	103	
Nickel Plating Layer	Nickel	7440-02-0			0.0360	0.01%	1.13%	121	
Inner electrode	Nickel	7440-02-0			0.5580	0.19%	17.44%	1879	
Tin Plating Layer	Tin	7440-31-5	0.0940	0.03%	2.94%	317			
FLASH Die	23.7400	Silicon Die	Silicon	7440-21-3	23.7400	7.99%	100.00%	79946	
			Misc	-	0.0000	0.00%	0.00%	0	
FLASH Die Attach - DAF Tape	0.2000	Adhesive Resin	Acryl copolymer	Trade Secret	0.0857	0.03%	42.86%	289	
			Epoxy	29690-82-2	0.0286	0.01%	14.29%	96	
			Hardener	Trade Secret	0.0286	0.01%	14.29%	96	
			Silica	7631-86-9	0.0571	0.02%	28.57%	192	
Controller Die	2.6406	Silicon Die	Silicon	7440-21-3	2.6406	0.89%	100.00%	8892	
			Misc	-	0.0000	0.00%	0.00%	0	
Controller Die Attach - Adhesive	0.1000	Adhesive	EP	-	0.0490	0.02%	48.96%	165	
			Silanamin, 1,1,1-Trimethyl-N-(trimethylsilyl)-, Hydrolyseprodukte mit Siliciumdioxid	68909-20-6	0.0340	0.01%	34.00%	114	
			Siliziumdioxid	7631-86-9	0.0170	0.01%	17.00%	57	
			Diisentrioxid	1309-37-1	0.0000	0.00%	0.03%	0	
			Calciumbis[4-[[3-[[2-hydroxy-3-[[4-methoxyphenyl]amino]carbonyl]-1-methyl]azo]-4-methylbenzoyl]amino]benzoesulfonat	43035-18-3	0.0000	0.00%	0.01%	0	
			N-(2,3-Dihydro-2-oxo-1H-benzimidazol-5-yl)-3-hydroxy-4-[[2-methoxy-5-methyl-4-[(methylamino)sulfonyl]phenyl]azo]na phthalin-2-carboxamid	51920-12-8	0.0000	0.00%	0.01%	0	
Bonding Wire	0.7965	Bonding wire	Gold	7440-57-5	0.7964	0.27%	99.99%	2682	
			Misc	-	0.0001	0.00%	0.01%	0	
Molding Compound	160.0000	Molding Compound	Silica (Fused)	60676-86-0 7631-86-9	138.7200	46.71%	86.70%	467149	
			Epoxy resin (1)	-	8.0000	2.69%	5.00%	26941	
			Epoxy resin (2)	-	4.0000	1.35%	2.50%	13470	
			Phenol resin (1)	-	4.8000	1.62%	3.00%	16164	
			Phenol resin (2)	-	4.0000	1.35%	2.50%	13470	
			Carbon black	1333-86-4	0.4800	0.16%	0.30%	1616	
			Solderpaste	0.5900	Solderpaste	Tin	7440-31-5	0.4720	0.16%
Silver	7440-22-4	0.0236				0.01%	4.00%	79	
Rosin, oligomers	65997-05-9	0.0354				0.01%	6.00%	119	
2-(2-Hexyloxyethoxy)ethanol	112-59-4	0.0354				0.01%	6.00%	119	
Indium	7440-74-6	0.0212				0.01%	3.60%	72	
Bismut	7440-69-9	0.0024				0.00%	0.40%	8	
Solder Balls	16.0061	Solder Balls	Tin	7440-31-5	15.4299	5.20%	96.40%	51961	
			Silver	7440-22-4	0.4802	0.16%	3.00%	1617	
			Copper	7440-50-8	0.0960	0.03%	0.60%	323	
Total					296.9504	100.0%		1000000	